

AP2141SG-13 AP2141SG-U AP2142SG-13 AP2142SG-U AP2151SG-13 AP2151SG-U AP2152SG-13 AP2152SG-U
 AP2161SG-13 AP2161SG-U AP2162SG-13 AP2162SG-U AP2171SG-13 AP2171SG-U AP2172SG-13 AP2172SG-U
 AP2181SG-13 AP2181SG-U AP2182SG-13 AP2182SG-U AP2191SG-13 AP2191SG-U AP2192SG-13 AP2192SG-U
 AP393ASG-13 AP393ASG-U AP393ASG-U AP5004-SG-13 AP5004-SG-U AP5004-SG-U

Part Number: **SOP-8L Green**
 Weight (mg): 75.926

Element	Material Group	Materials	CAS (if applicable)	Average mass homogeneous Material(%)	Percent of whole (%)	Mass (mg)	ppm Homogeneous Material	ppm overall
Die,Mosfet	Doped silicon	Doped silicon *	7440-21-3	100.00%	7.892	5.992	1000000	78923
SOP-8L leadframe	CDA 194	Cu	7440-50-8	97.40%	51.403	39.029	974000	500670
		Fe	1309-37-1	2.40%			24000	12337
		P	7723-14-0	0.08%			800	411
		Zn	7440-66-6	0.12%			1200	617
	Pure silver	Ag	7440-22-4	100.00%	0.940	0.714	1000000	9404
Bonding wire	2.0mil	Au	7440-57-5	100.00%	0.946	0.719	1000000	9464
Molding compound	EME-G600	Epoxy Resin	-----	5.00%	34.281	26.028	50000	17140
		Phenol Resin	-----	5.00%			50000	17140
		Bismuth/Bismuth compound	-----	0.05%			500	171
		SiO2	60676-86-0	87.45%			874500	298785
		Cresol Novolac	29690-82-2	2.00%			20000	6856
		C	1333-86-4	0.50%			5000	1714
Die attached epoxy	84-1 LMISR4	Ag	7440-22-4	75.00%	2.971	2.256	750000	22281
		epoxy resin	Trade secret	20.00%			200000	5942
		curing agent & hardener	Trade secret	5.00%			50000	1485
Tin solder	Pure Tin	Sn	7440-31-5	100.00%	1.566	1.189	1000000	15659
					100.00	75.926		1000000

Tolerance ±10%

This data is based on information provided by our suppliers. We believe it to be correct but do not routinely validate it by measurement. It is for guidance only and Diodes Inc. does not guarantee its absolute accuracy or completeness

* The Silicon Chip is doped at atomic levels with trace amounts of elements that may include Phosphorus, Boron, Arsenic, and other elements. Metalization may include Titanium, Nickel, Aluminum, Silver or Gold. These substances are not reported where their concentration is less than the minimum reportable level per the guidelines specified in the Tables of EIA JIG-101, Material Composition Declaration for Electronic Products.

This product or product family does not contain any of the following substances except as **CURRENTLY** exempted by ELV II and RoHS and reported above:

Antimony compounds	Organic tin compounds
Asbestos	Ozone Depleting Substances - Class I (CFCs, HBFCs, etc.)
Azo compounds	Ozone Depleting Substances - Class II (HCFCs)
Cadmium and cadmium compounds	Perfluorooctane Sulphonate (PFOS) or related compounds
Certain Shortchain Chlorinated Paraffins	Polybrominated biphenyls (PBB) and Polybrominated diphenyl ethers (PBDE) including DecaBDE
Chlorinated organic compounds	Polychlorinated Biphenyls (PCBs)
Halogens	Polychlorinated Naphthalenes (> 3 chlorine atoms)
Hexavalent chromium compounds	Radioactive Substances
Lead and lead compounds	Tributyl Tin (TBT) and Triphenyl Tin (TPT)
Mercury and mercury compounds	Tributyl Tin Oxide (TBTO)